

L Number	Hits	Search Text	DB	Time stamp
1	752	RF and platen	USPAT	2001/09/28 10:52
2	915840	heat\$	USPAT	2001/09/28 10:51
3	4579	"inductively coupled plasma" or ICP	USPAT	2001/09/28 10:51
4	76	(RF and platen) with heat\$	USPAT	2001/09/28 10:54
5	4	("inductively coupled plasma" or ICP) and ((RF and platen) with heat\$)	USPAT	2001/09/28 10:53
6	61	((("hydrogen plasma") with clean\$) and sputtering	USPAT	2001/09/28 10:54
7	0	((RF and platen) with heat\$) and (((("hydrogen plasma") with clean\$) and sputtering)	USPAT	2001/09/28 10:54
8	30	(RF and platen) and ("inductively coupled plasma" or ICP)	USPAT	2001/09/28 10:55
9	1	((("hydrogen plasma") with clean\$) and sputtering) and ((RF and platen) and ("inductively coupled plasma" or ICP))	USPAT	2001/09/28 10:55
-	98	("hydrogen plasma") with clean\$	USPAT	2001/09/28 10:50
-	42	(insulating or dielectric) and (((("hydrogen plasma") with clean\$) and sputtering)	USPAT	2001/06/05 09:58
-	90	("hydrogen plasma") and clean\$	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:14
-	56894	sputtering	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:14
-	586395	insulating or dielectric	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:14
-	1	(insulating or dielectric) and (((("hydrogen plasma") and clean\$) and sputtering)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:15
-	5	((("hydrogen plasma") and clean\$) and sputtering	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:16
-	11	((("hydrogen plasma") and clean\$) and (insulating or dielectric)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:17
-	799788	semiconductor	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:17
-	6	((("hydrogen plasma") and clean\$) and (insulating or dielectric)) and semiconductor	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/01 12:22
-	134	438/677.ccls.	USPAT	2001/06/01 12:24
-	2	((("hydrogen plasma") with clean\$) and 438/677.ccls.	USPAT	2001/06/01 12:24
-	308	438/685.ccls.	USPAT	2001/06/01 12:29
-	13	438/685.ccls. and "hydrogen plasma"	USPAT	2001/06/01 13:14
-	333	438/688.ccls.	USPAT	2001/06/01 12:36
-	9	"hydrogen plasma" and 438/688.ccls.	USPAT	2001/06/01 13:13
-	270	438/906.ccls.	USPAT	2001/06/01 13:13
-	12	"hydrogen plasma" and 438/906.ccls.	USPAT	2001/06/01 13:19
-	267	438/974.ccls.	USPAT	2001/06/01 13:19
-	11	"hydrogen plasma" and 438/974.ccls.	USPAT	2001/06/01 13:19
-	3	sputtering and ("hydrogen plasma" and 438/974.ccls.)	USPAT	2001/06/01 14:28
-	186	438/597.CCLS.	USPAT	2001/06/01 14:29
-	1181	"hydrogen plasma"	USPAT	2001/06/01 14:30
-	50771	sputtering	USPAT	2001/06/01 14:33
-	543	"hydrogen plasma" and sputtering	USPAT	2001/06/01 14:33
-	1	438/597.CCLS. and ("hydrogen plasma" and sputtering)	USPAT	2001/06/01 14:33

-	3284	438/618-640.ccls.	USPAT	2001/06/01 14:52
-	18	("hydrogen plasma" and sputtering) and 438/618-640.ccls.	USPAT	2001/06/01 14:52
-	299947	insulating or dielectric	USPAT	2001/06/01 14:55
-	17	((("hydrogen plasma" and sputtering) and 438/618-640.ccls.) and (insulating or dielectric))	USPAT	2001/06/01 15:17
-	2202	438/642-656.ccls.	USPAT	2001/06/01 15:17
-	411	("hydrogen plasma" and sputtering) and (insulating or dielectric)	USPAT	2001/06/01 15:18
-	16	438/642-656.ccls. and ((("hydrogen plasma" and sputtering) and (insulating or dielectric)))	USPAT	2001/06/01 15:23
-	203	204/192.37.ccls.	USPAT	2001/06/01 15:24
-	4	("hydrogen plasma" and sputtering) and 204/192.37.ccls.	USPAT	2001/06/01 15:24
-	279	204/192.17.ccls.	USPAT	2001/06/01 15:24
-	4	("hydrogen plasma" and sputtering) and 204/192.17.ccls.	USPAT	2001/06/01 15:26
-	304	204/192.3.ccls.	USPAT	2001/06/01 15:26
-	4	("hydrogen plasma" and sputtering) and 204/192.3.ccls.	USPAT	2001/06/01 15:27
-	1	("5108951").PN.	USPAT	2001/06/05 09:58
-	1	("3844924").PN.	USPAT	2001/06/05 15:29
-	1	("3616401").PN.	USPAT	2001/06/05 15:30
-	79	"aluminum nitride" with "aluminum alloy"	USPAT	2001/06/05 15:32

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